



Selective Line 3D

AOI integration module for selective solder joint inspection



- powerful AOI integration module
- combined 2D/3D imaging technologies
- reproducible inspection of selective solder joints
- modular overall package with hardware and software
- easy mechanical and electrical integration

Technichal specifications

Selective Line 3D - AOI integration module



Utilisation concept

- powerful automatic optical inspection module for the inspection of selective solder joints
- flexible integration into the periphery of selective soldering systems
- wide range of communication interface support
- two versions: combined 2D/3D technology or 2D technology

Maximum fault detection

- determination of solder flow, solder volume and pin height of THT solder joints
- flexible inspection methods and individually expandable inspection functions
- outstanding ease of use with the system software PILOT AOI
- fast and intuitive test program creation
- verification and repair station software

MES/Industry 4.0

- flexible data interfaces for MES and traceability connections
- data management and comprehensive fault evaluation via PILOT Connect

Technichal specifications

Inspection module	AOI integration module for selective solder joint inspection
image capturing 3D	fringe projection method
image capturing 2D	multispectral top and quattro lighting
resolution x/y	20 µm
resolution z	1 µm
FOV	40 mm x 40 mm (2D: up to 50 mm x 50 mm)
component clearance	40 mm (3D) / flexible up to 100 mm (2D)
inspection height 3D	13 mm
dimensions integration module (W x D x H)	3D module: 300 mm x 300 mm x 450 mm 2D module: 180 mm x 160 mm x 420 mm
power requirement	230 VAC / 0.4 kVA

